Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	144	basol\$-b\$.in. and electrochemical adj mechanical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 16:31
S3	144	basol\$-b\$.in. and electrochemical adj mechanical\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 16:39
S5	90	etch\$3 with sweep	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/04/27 13:09
S4	27	basol\$-b\$.in. and electrochemical adj mechanical\$2 and temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:09
S6	1	etch\$3 with sweep same (suppress\$4 accelerat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:25
S9	138	surface adj moiety and (pad sweep)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:34
S8	510	surface adj moiety	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:34
S7	3	polish\$3 with sweep same (suppress\$4 accelerat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:34
S11	0	surface adj moiety and (pad sweep) and chemical adj mechanical adj polishin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:38

S10	110	surface adj moiety and (pad sweep) and (polishing etching removing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:38
S14	401	temperature with electroplating with copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:45
S15	6	("6004880" "6090239" "6224737" "6245676" "6284121" "6303014"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/27 13:53
S16	2	surface adj moiety and chemical adj mechanical adj polishing and temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:01
S17	134	accelerator with (adsor\$5 absor\$5) with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:02
S18	33	accelerator with (adsor\$5 absor\$5) with temperature and mechanical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:03
S20	128	accelerator with (adsor\$5 absor\$5) and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:10
S21	9	accelerator with (adsor\$5 absor\$5) same temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:11
S19	2	accelerator with (adsor\$5 absor\$5) with temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:11
S24	8	brighten\$3 with (adsor\$5 absor\$5) same temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:12

S23	1	brighten\$3 with (adsor\$5 absor\$5) with temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:12
S22	0	brighten\$2 with (adsor\$5 absor\$5) with temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:12
S12	3	surface adj moiety and (pad sweep) and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:16
S26	1050	chelat\$3 and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:17
S25	4	surface adj moiety and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:17
S28	19	chelat\$3 with temperature and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:18
S27	46986	chelat\$3 with temperatureand chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:18
S29	19	chelat\$3 with temperature and (chemical electrochemical) adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:31
S31	61	S30 not S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:32
S32	79	sawtooth and ("204" "205" "451"). clas.	US-PGPUB	OR	ON	2006/04/28 15:30

S33	239	(accelerator accelerating brightener brightening) with composition same electroplat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:51
S30	80	(chelat\$3 accelerator accelerating brightener brightening) with temperature and (chemical electrochemical) adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:51
S13	20	("20010015321" "4080513" "6004880" "6090239" "6224737" "6245676" "62 84121" "6303014" "6344129" "653411 6").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:53
S36	322	electroplat\$ with (wafer semiconductor microelectronic microfeature) and (paddle stirring agitating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
S35	272	electroplat\$ with (wafer semiconductor microelectronic microfeature) and (paddle stirring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
S34	5384	electroplat\$ with (wafer semiconductor microelectronic microfeature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
S37	87	electroplat\$ with copper with (wafer semiconductor microelectronic microfeature) and (paddle stirring agitating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:55
S40	1	"5807165".PN.	USPAT; USOCR	OR	ON	2006/05/11 10:56
S38	29	electroplat\$ with copper with (wafer semiconductor microelectronic microfeature) and uzoh.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:56

S43	33	("3421994" "3511758" "4302316" "4532017" "4626331" "4793895" "4821466" "4861449" "4934102" "5078801" "5167792" "5168887" "5225034" "5240552" "5449313" "5464519" "5492594" "5516412" "5522975" "5534106" "5543032" "5567300" "5575706" "5620581" "5624300" "5637185" "5685766" "5744019" "5755859" "5793272" "5807165").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/11 10:57
S42	33	("3421994" "3511758" "4302316" "4532017" "4626331" "4793895" "4821466" "4861449" "4934102" "5078801" "5167792" "5168887" "5225034" "5240552" "5449313" "5464519" "5492594" "5516412" "5522975" "5534106" "5543032" "5567300" "5575706" "5620581" "5624300" "5637185" "5685766" "5744019" "5755859" "5793272" "5807165").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/11 10:57
S41	104	uzoh.in. and ("204" "205").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:57
S39	84	electroplat\$ with (wafer semiconductor microelectronic microfeature) and uzoh.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:57
S47	5	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn.	USPAT	OR	ON	2006/05/11 11:17
S46	0	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn. and accelerant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:17
S45	0	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn. and accelerator	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:17
S44	15	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:17

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S48	73	205/640-686.ccls. and (brightening brightener)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:45
S51	84	205/640-686.ccls. and (brightening brightener accelerator accelerant accelerating) and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:46
S50	122	205/640-686.ccls. and (brightening brightener accelerator accelerant accelerating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:46
S49	94	205/640-686.ccls. and (brightening brightener accelerator accelerant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:46
S1	313	basol\$-b\$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:09
L2	2	"6921551".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:09
L5	1210	temperature with control\$4 same ((wafer adj chuck) (substrate adj support))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:19
L6	88	temperature with control\$4 same ((wafer adj chuck) (substrate adj support)) and electroplat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:31
L9	14	uzoh.in. and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:54
L7	1	temperature with control\$4 same ((wafer adj chuck) (substrate adj support)) same electroplat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:54